

# **Description**

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

#### **Features**

- $20V,4A,R_{DS(ON).max}=27m\Omega@V_{GS}=4.5V$
- Improved dv/dt capability
- ♦ Fast switching
- Green device available

### **Applications**

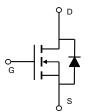
- Battery protection
- Load switch
- Power management

# **Product Summary**

 $\begin{array}{ll} V_{DSS} & 20V \\ R_{DS(on).max} @\ V_{GS} \text{=} 4.5V & 27m\Omega \\ I_D & 4A \end{array}$ 

# **Pin Configuration**





SOT-23-6

Schematic

# Absolute Maximum Ratings TA = 25°C unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DSS</sub>	20	V
Continuous drain current ( T <sub>A</sub> = 25°C )		4	A
Continuous drain current ( T <sub>A</sub> = 100°C )	I <sub>D</sub>	2.5	A
Pulsed drain current <sup>1)</sup>	I <sub>DM</sub>	16	А
Gate-Source voltage	V <sub>GSS</sub>	±12	V
Power Dissipation ( T <sub>A</sub> = 25°C )	P <sub>D</sub>	1.25	W
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C
Operating Junction Temperature Range	TJ	-55 to +150	°C

#### **Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	Reja	100	°C/W



Shenzhen VSEEI Semiconductor Co., Ltd

# **Package Marking and Ordering Information**

Device	Device Package	Marking	
VSMLNSD8205-S6	SOT-23-6	VSMLNSD8205-S6	

# Electrical Characteristics T<sub>J</sub> = 25°C unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0 V, I <sub>D</sub> =250uA	20			V
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	0.5	0.75	1.0	V
Drain-source leakage current		V <sub>DS</sub> =20 V, V <sub>GS</sub> =0 V, T <sub>J</sub> = 25°C			1	μА
	loss	V <sub>DS</sub> =16 V, V <sub>GS</sub> =0 V, T <sub>J</sub> = 125°C			10	μA
Gate leakage current, Forward	Igssf	V <sub>GS</sub> =12 V, V <sub>DS</sub> =0 V			100	nA
Gate leakage current, Reverse	I <sub>GSSR</sub>	V <sub>GS</sub> =-12 V, V <sub>DS</sub> =0 V			-100	nA
Drain course en etate registance	В	V <sub>GS</sub> =4.5 V, I <sub>D</sub> =4 A		19	27	mΩ
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =2.5 V, I <sub>D</sub> =3 A		23	37	mΩ
Forward transconductance	g <sub>fs</sub>	V <sub>DS</sub> =5 V , I <sub>D</sub> =4A		11		S
Dynamic characteristics						
Input capacitance	Ciss			373		pF
Output capacitance	Coss	V <sub>DS</sub> = 8 V, V <sub>GS</sub> = 0 V, F = 1MHz		70.4		
Reverse transfer capacitance	C <sub>rss</sub>			57		
Turn-on delay time	t <sub>d(on)</sub>			17.8		ns
Rise time	tr	V <sub>DD</sub> = 10V,V <sub>GS</sub> =4.5V, I <sub>D</sub> =4 A		27.6		
Turn-off delay time	t <sub>d(off)</sub>	- VDD - 10V,VGS-4.0V, ID -4 A		44		
Fall time	t <sub>f</sub>			28.6		
Gate resistance	R <sub>g</sub>	V <sub>GS</sub> =0V,V <sub>DS</sub> =0V,f=1MHz		9		Ω
Gate charge characteristics						
Gate to source charge	Q <sub>gs</sub>			2.3		
Gate to drain charge	$Q_{gd}$	V <sub>DS</sub> =10V, I <sub>D</sub> =4A, V <sub>GS</sub> = 4.5V		1.4		nC
Gate charge total	Qg			11.7		
Drain-Source diode characteris	tics and Maxir	num Ratings			•	
Continuous Source Current	Is				4	А
Pulsed Source Current <sup>2)</sup>	I <sub>SM</sub>				16	А
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =4A, T <sub>J</sub> =25℃			1.2	V

#### Notes:

<sup>1:</sup> Repetitive Rating: Pulse width limited by maximum junction temperature.

<sup>2:</sup> Pulse Test: Pulse Width  $\leq 300~\mu$  s, Duty Cycle  $\leq 2\%$ .



# **Electrical Characteristics Diagrams**

Figure 1. Typ. Output Characteristics

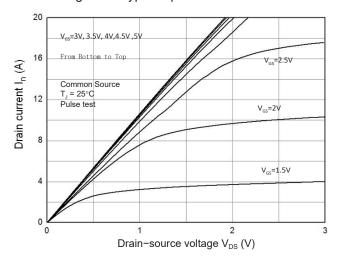


Figure 2. Transfer Characteristics

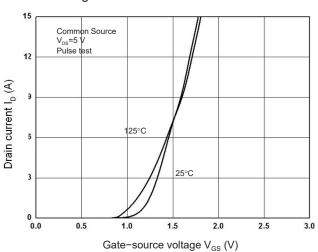


Figure 3. Capacitance Characteristics

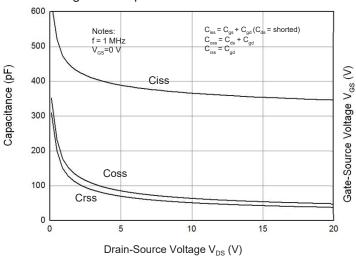


Figure 4. Gate Charge Waveform

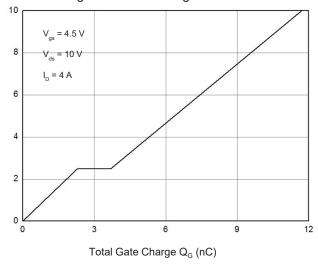


Figure 5. Body-Diode Characteristics

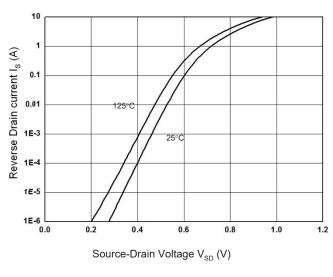


Figure 6. Rdson-Drain Current

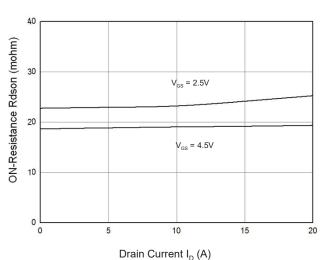




Figure 7. Rdson-Junction Temperature(°C)

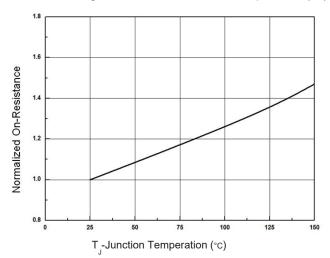


Figure 8. Maximum Safe Operating Area

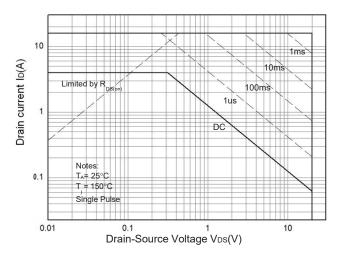
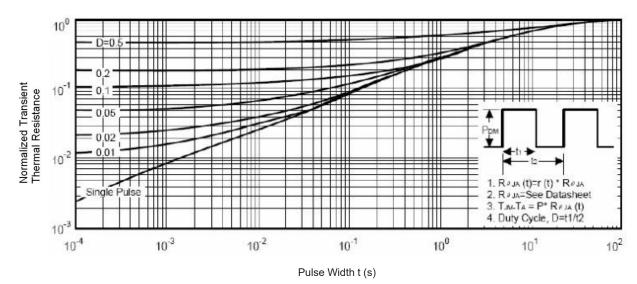


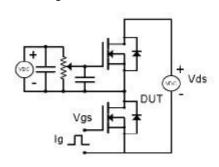
Figure 9. Normalized Maximum Transient Thermal Impedance (RthJA)





# **Test Circuit & Waveform**

Figure 8. Gate Charge Test Circuit & Waveform



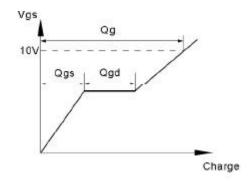
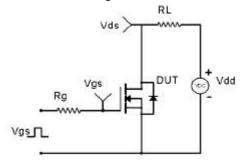


Figure 9. Resistive Switching Test Circuit & Waveforms



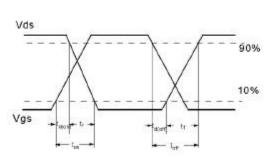
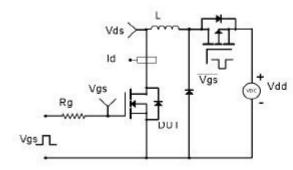


Figure 10. Unclamped Inductive Switching (UIS) Test Circuit & Waveform



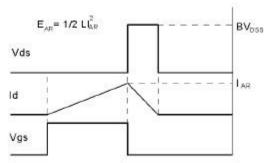


Figure 11. Diode Recovery Circuit & Waveform

